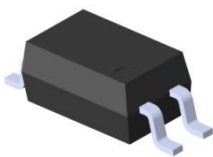
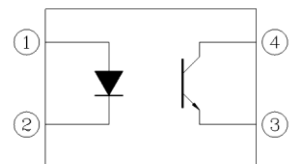


### 4 PIN SSOP PHOTOTRANSISTOR PHOTOCOUPLER EL3H7U-G Series

Preliminary



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

#### Features:

- Halogens free  
(Br <900 ppm , Cl <900 ppm , Br+Cl < 1500 ppm)
- Current transfer ratio  
(CTR: 100~560% at  $I_F = 0.5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- Operating temperature  $-40^\circ\text{C} \sim 125^\circ\text{C}$
- High isolation voltage between input and output (Viso=3750 V rms )
- Compact 4 Pin SSOP with a 2.0 mm profile
- Compliance with EU REACH
- UL and cUL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

This is a preliminary specification intended for design purposes and subject to change without prior notice.

#### Description

The EL3H7U-G series devices consist of an infrared emitting diode, optically coupled to a phototransistor detector encapsulated with green compound.

They are packaged in a 4-pin small outline SMD package.

#### Applications

- DC-DC Converters
- Programmable controllers
- Telecommunication equipments
- Signal transmission between circuits of different potentials and impedances

# Absolute Maximum Ratings (T<sub>A</sub>=25°C) \*1

	Parameter	Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	20	mA
	Reverse voltage	V <sub>R</sub>	5	V
	Power dissipation	P <sub>D</sub>	40	mW
Output	Collector current	I <sub>C</sub>	30	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	60	V
	Emitter-Collector voltage	V <sub>ECO</sub>	5	V
	Power dissipation	P <sub>C</sub>	150	mW
	Total Power Dissipation	P <sub>TOT</sub>	200	mW
	Isolation Voltage*2	V <sub>ISO</sub>	3750	Vrms
	Operating temperature	T <sub>OPR</sub>	-40 ~ +125	°C
	Storage temperature	T <sub>STG</sub>	-40 ~ +150	°C
	Soldering Temperature*3	T <sub>SOL</sub>	260	°C

## Notes:

\*1 Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability. The absolute maximum Ratings are stress only T<sub>A</sub>=25°C unless otherwise specified.

\*2 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*3 For 10 seconds

**Electro-Optical Characteristics (T<sub>A</sub>=25°C unless specified otherwise)**

**Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V <sub>F</sub>	-	1.3	1.7	V	I <sub>F</sub> = 1mA
Reverse current	I <sub>R</sub>	-	-	10	μA	V <sub>R</sub> = 5V
Input capacitance	C <sub>in</sub>	-	30	250	pF	V = 0, f = 1kHz

**Output**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I <sub>CEO</sub>	-	-	100	nA	V <sub>CE</sub> = 20V, I <sub>F</sub> = 0mA
Collector-Emitter breakdown voltage	BV <sub>CEO</sub>	60	-	-	V	I <sub>C</sub> = 0.1mA
Emitter-Collector breakdown voltage	BV <sub>ECO</sub>	5	-	-	V	I <sub>E</sub> = 0.1mA

**Transfer Characteristics (T<sub>A</sub>=25°C unless specified otherwise)**

Parameter	Symbo	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL3H7U	50	-	600	%	I <sub>F</sub> = 0.5mA, V <sub>CE</sub> = 5V
	EL3H7UA	100	-	200	%	
	EL3H7UB	150	-	300	%	
	EL3H7UC	200	-	400	%	
Collector-Emitter saturation voltage	V <sub>CE(sat)</sub>	-	-	0.4	V	I <sub>F</sub> = 3mA, I <sub>C</sub> = 1.6mA
Isolation resistance	R <sub>IO</sub>	5×10 <sup>10</sup>	-	-	Ω	V <sub>IO</sub> = 500Vdc, 40~60% R.H.
Floating capacitance	C <sub>IO</sub>	-	0.3	1.0	pF	V <sub>IO</sub> = 0, f = 1MHz
Rise time	t <sub>r</sub>	-	8	-	μs	V <sub>CE</sub> = 2V, I <sub>C</sub> = 2mA, R <sub>L</sub> = 100Ω
Fall time	t <sub>f</sub>	-	10	-	μs	

\* Typical values at T<sub>A</sub> = 25°C

## Typical Electro-Optical Characteristics Curves\*

Figure 1. Forward Current vs Forward Voltage

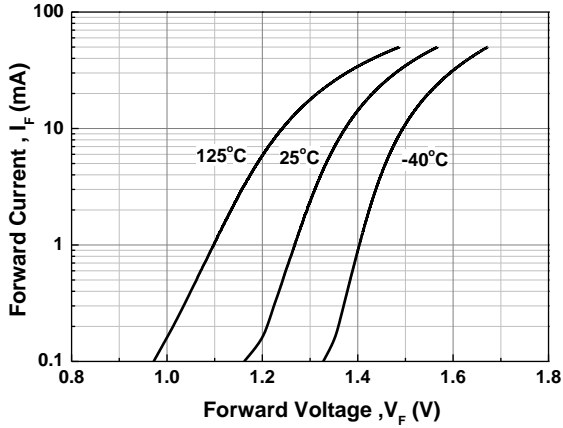


Figure 2. Collector Current vs Forward Current

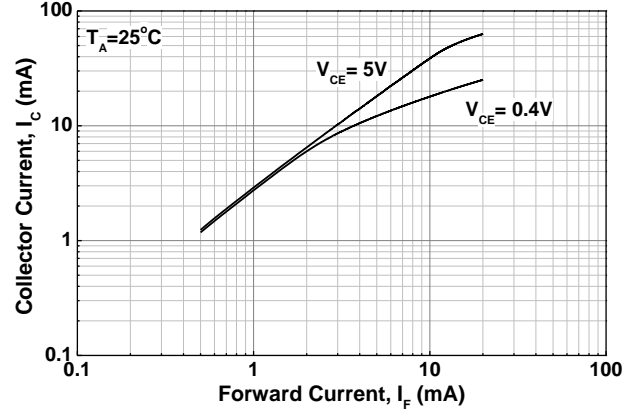


Figure 3. Normalized Current Transfer Ratio vs Forward Current

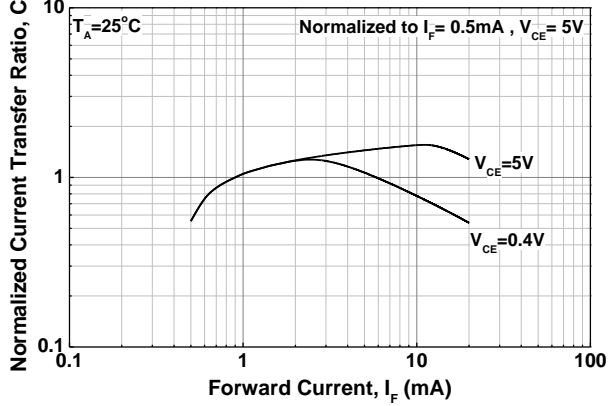


Figure 4. Collector Current vs Collector-Emitter Voltage

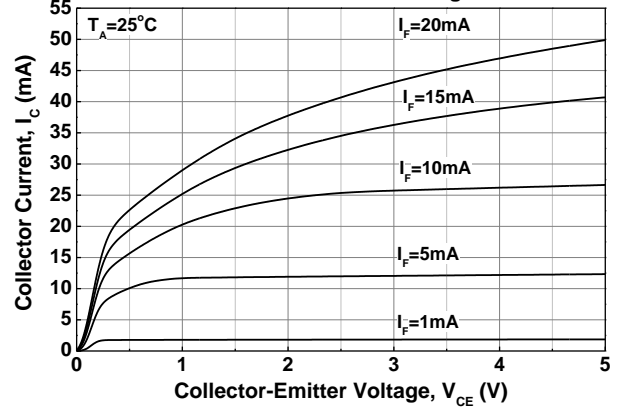


Figure 5. Collector Current vs Collector-Emitter Voltage

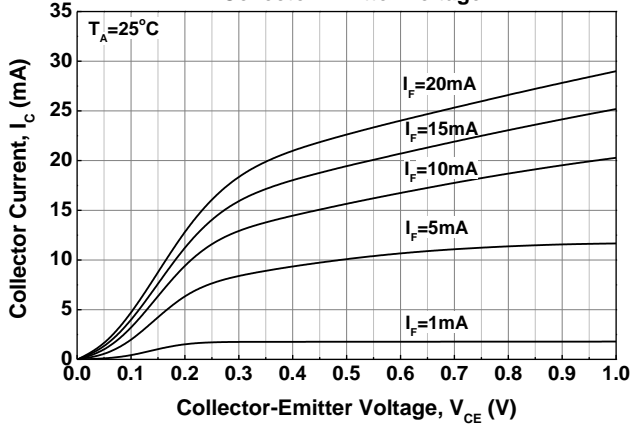


Figure 6. Collector Current vs Ambient Temperature

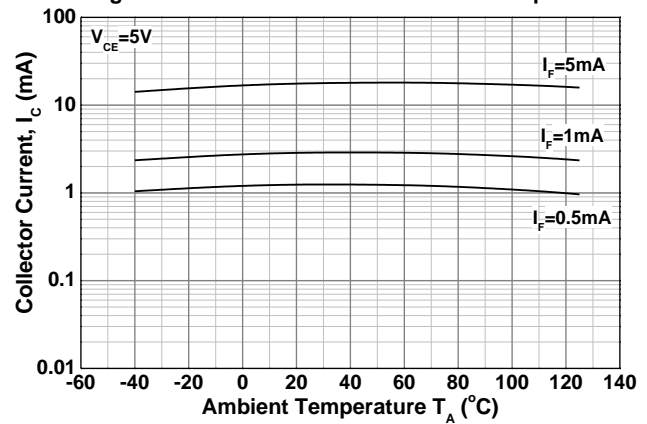


Figure 7. Normalized Current Transfer Ratio vs Ambient Temperature

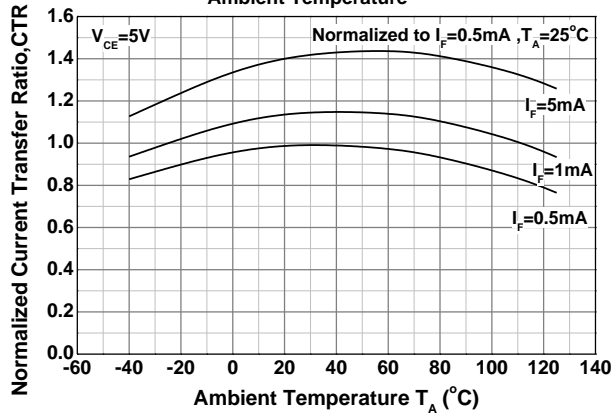


Figure 8. Dark Current vs Ambient Temperature

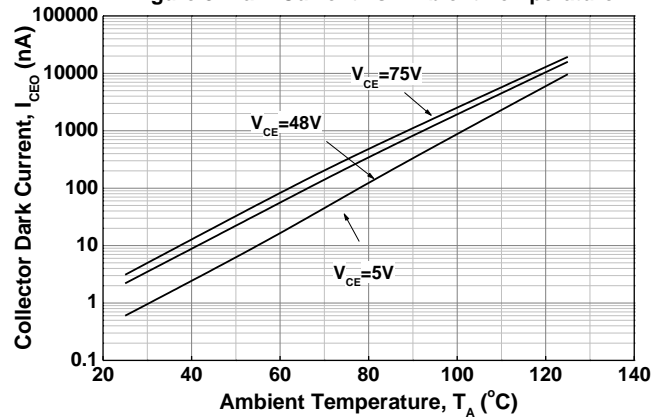


Figure 9. Switching Time vs Load Resistance

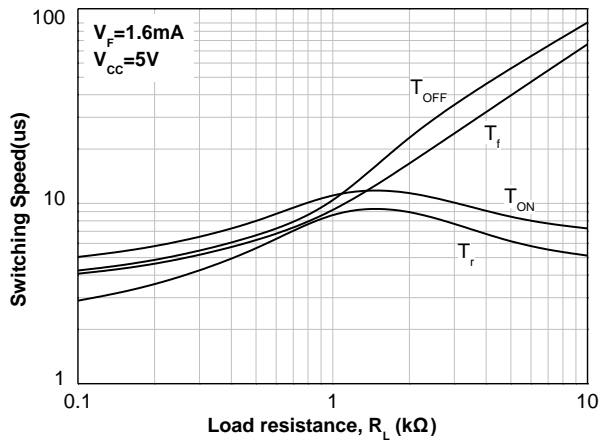
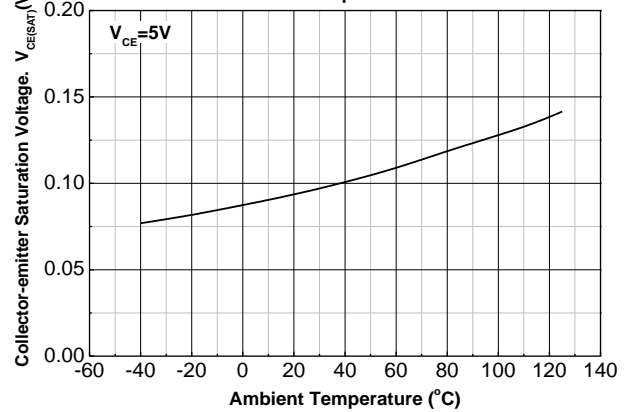


Figure 10. Collector-emitter Saturation Voltage vs Ambient Temperature



\*Please be aware that all datas in the graph are just for reference and not for guaranteed by production test.

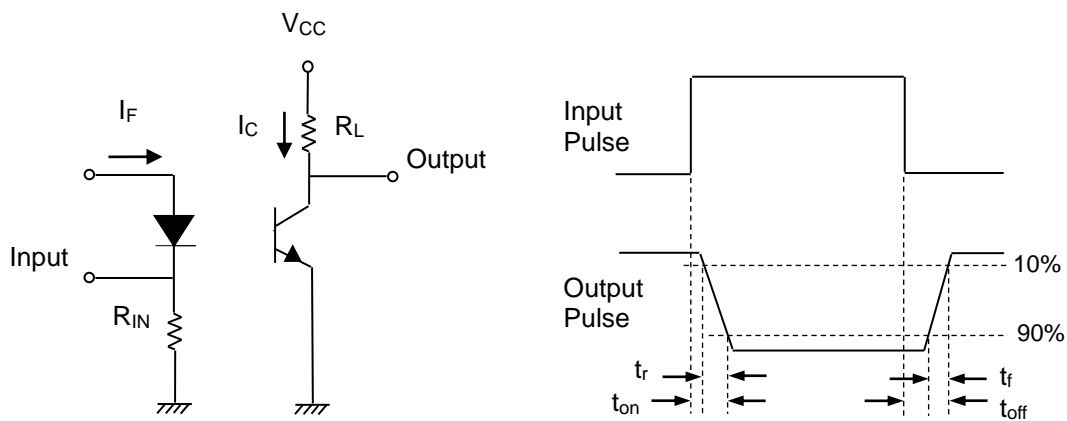


Figure 13. Switching Time Test Circuit & Waveforms

## Order Information

Part Number

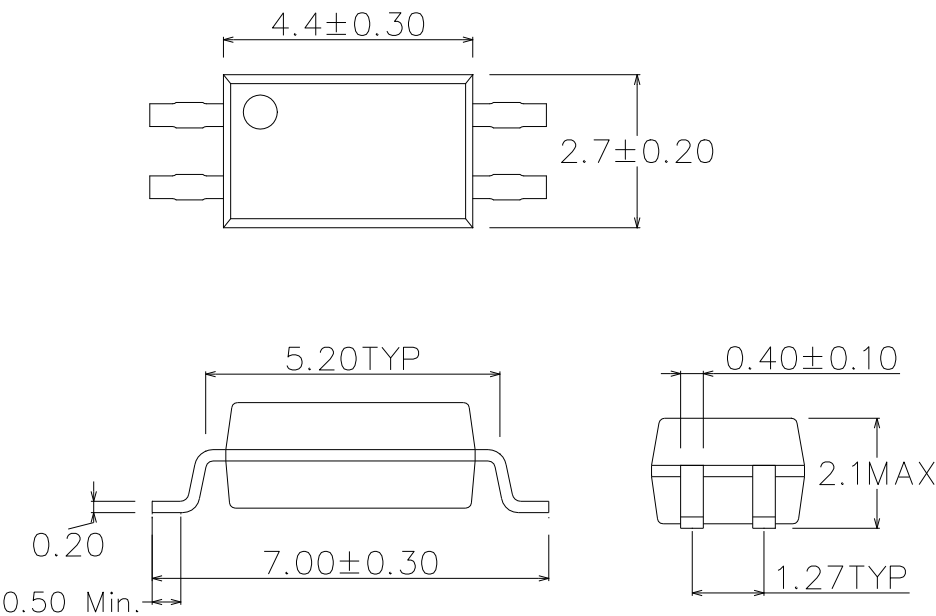
EL3H7U(X)(Y)-VG

Note

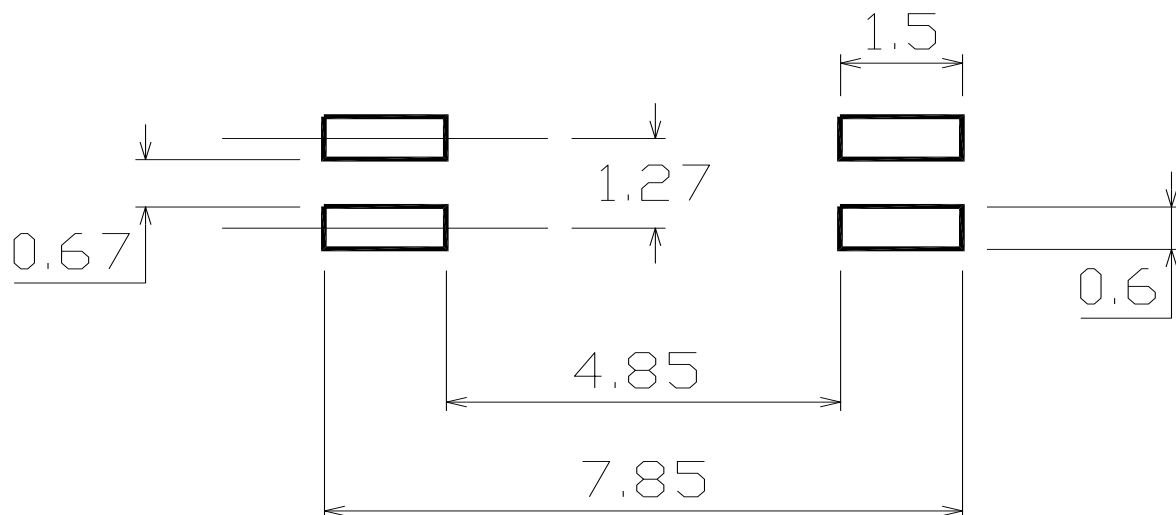
- X = CTR Rank (A, B , C or none)
- Y = Tape and reel option (TA, TB or none)
- V = VDE (optional)
- G = Halogens free

Option	Description	Packing quantity
(TA)	TA Tape & reel option	5000 units per reel
(TB)	TB Tape & reel option	5000 units per reel
(TA)-V	TA Tape & reel option + VDE	5000 units per reel
(TB)-V	TB Tape & reel option + VDE	5000 units per reel

Package Dimension (Dimensions in mm)



Recommended pad layout for surface mount leadform

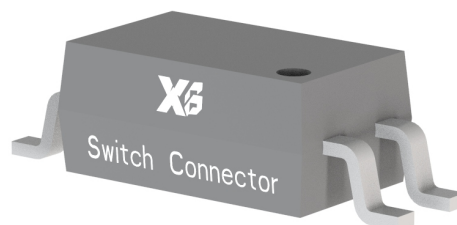


## Device Marking



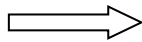
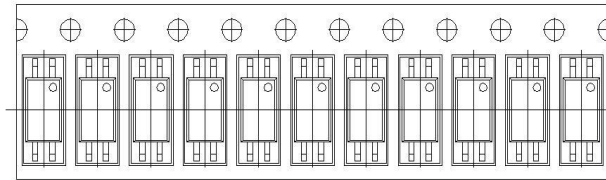
## Notes

EL denotes XI BNANG  
3H7U denotes Device Number  
A denotes CTR Rank  
Y denotes 1 digit Year code WW  
denotes 2 digit Week code  
V denotes VDE (optional)



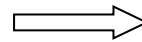
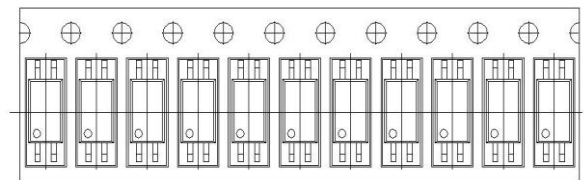
## Tape & Reel Packing Specifications

### Option TA



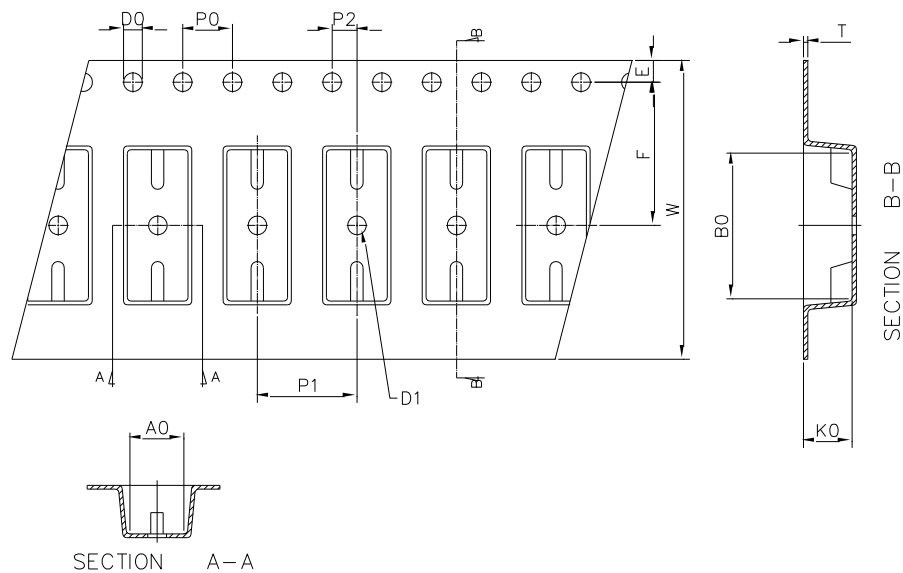
Direction of feed from reel

### Option TB



Direction of feed from reel

## Tape dimensions



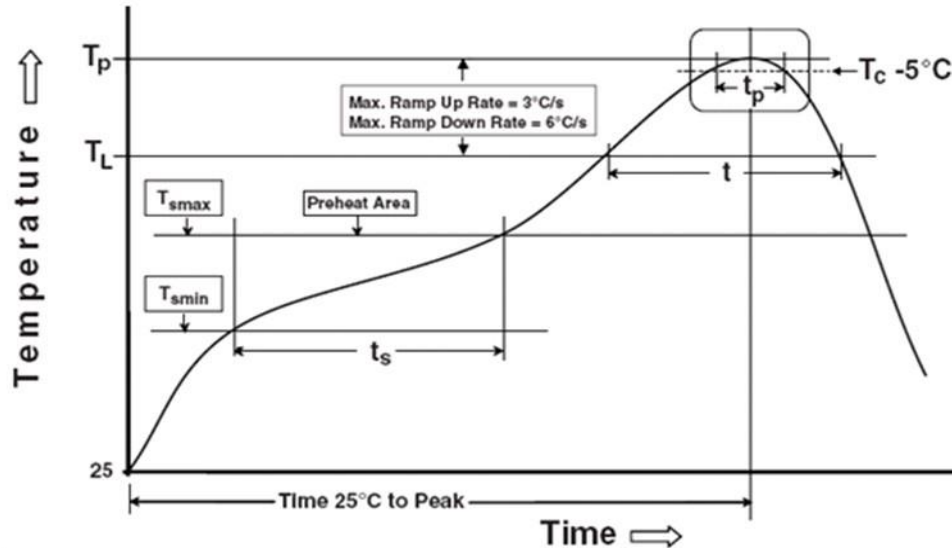
Dimension No.	A0	B0	D0	D1	E	F
Dimension (mm)	$3.00 \pm 0.10$	$7.45 \pm 0.10$	$1.50 + 0.1/-0$	$1.50 \pm 0.10$	$1.75 \pm 0.10$	$5.50 \pm 0.10$
Dimension No.	P0	P1	P2	t	W	K0
Dimension (mm)	$4.00 \pm 0.15$	$8.00 \pm 0.10$	$2.00 \pm 0.10$	$0.30 \pm 0.05$	$12.1 \pm 0.2$	$2.45 \pm 0.1$



## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ C$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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